

PCN – Process Change Notification

Change:	EMPCB.SMAFSTJ.C.HT
Date:	2017/05/16
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Affected Products

Model#	Part Number	Changes
SMA(F)ST_ FOR PCB EDGE MOUNT_Ni PLATING Connector Solder Attachment	EMPCB.SMAFSTJ.C. HT	1. Amend Package Rule.

Type of Change

- Hardware Modification
 Production Process Advance
 Others –Amend Package Rule
-

Description of Change

1. Amend Package Rule.

Schedule

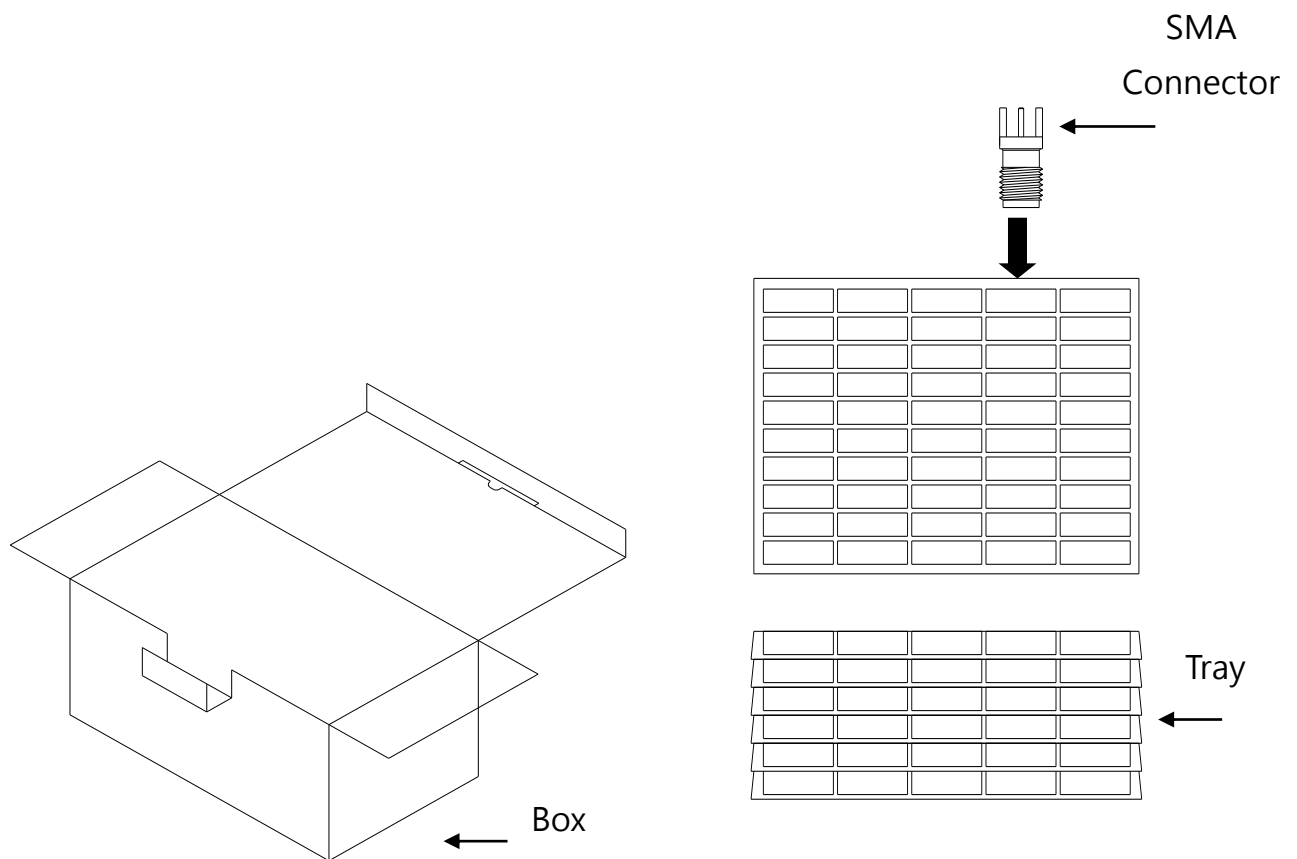
2017, May, Taoglas will provide new package rule into production.

Forecast Estimated Transition Date

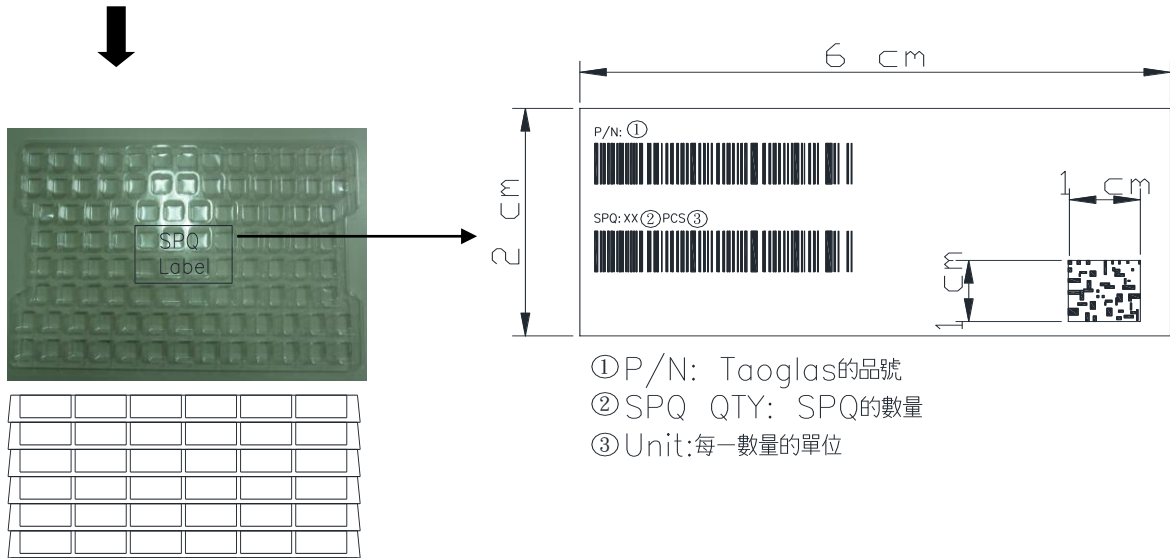
May/2017

Illustration of Change

Old Packaging

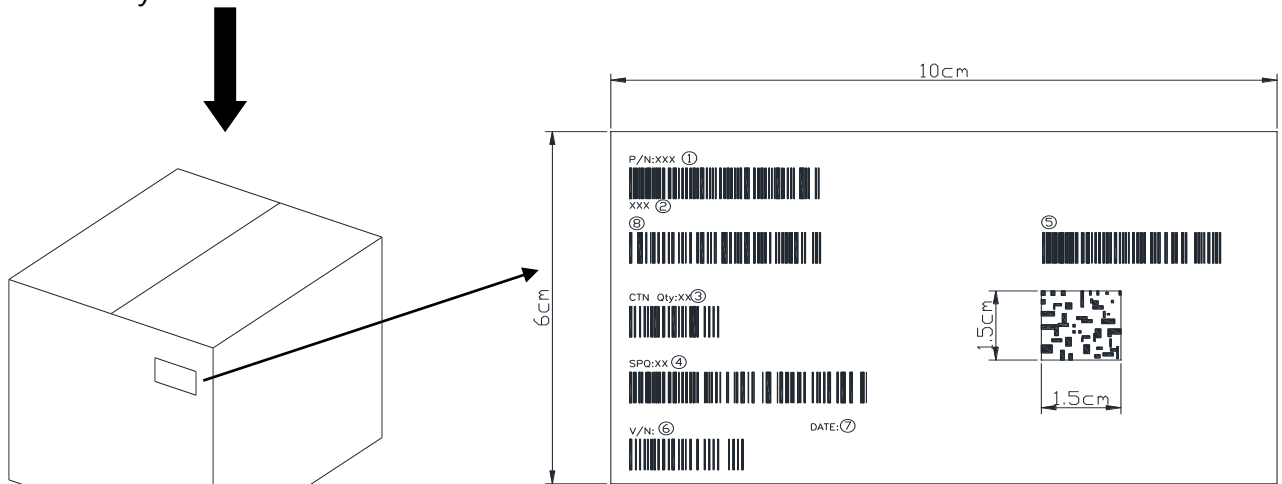


New Packaging



- ① P/N: Taoglas的品號
- ② SPQ QTY: SPQ的數量
- ③ Unit: 每一數量的單位

500pcs/Tray * 6 (Vacuum)
Tray dimension: 268*180mm



- 1.P/N: Taoglas的品號
 - 2.Description: Taoglas的品名
 - 3.CTN QTY: 外箱數量
 - 4.SPQ QTY: SPQ數量
 - 5.Purchase No.: Taoglas採購單號
 - 6.V/N: 廠商品號
 - 7.預定銷貨日, 格式為DATE:yyyy/mm/dd
 - 8.Batch No.: Taoglas的批號, 請廠商依下列批號原則建立每批進廠批號, 廠商碼將另行通知。
- I 03 001 0001
T: 正品 03: 年 001: 廠商碼 0001: 流水碼
P: 備品

3000PCS / Carton
(375*285*155mm)